



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-05-07
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDRF CHAMPION	Representative title	MDRF Material Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32H562RGV6	62GB*484XXXX	A	998Z	2025-05-07
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	184	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFN	8x8	68	Flat	
Comment	Package : B029 VFQFPN 8X8X1.0 68L PITCH 0.4 DM00319327			

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-21st January 2025				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	62GB*484XXX		183.836	600000	1000000	
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	7.807	mg	supplier	die	Silicon (Si)	7440-21-3		7.379	mg	945164	40140
				supplier	metallization	Aluminium (Al)	7429-90-5		0.047	mg	6053	257
				supplier	metallization	Copper (Cu)	7440-50-8		0.141	mg	18037	766
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	121	5
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.025	mg	3147	134
				supplier	metallization	Titanium (Ti)	7440-32-6		0.006	mg	726	31
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	121	5
				supplier	Passivation	Silicon Nitride	12033-89-5		0.034	mg	4358	185
				supplier	Passivation	Silicon Oxide	7631-86-9		0.174	mg	22273	946
				Glue Epoxy (EN4900GC)	Other Organic Materials	0.590	mg	supplier	Organic Compounds	Acrylic resin	Proprietary	
supplier	Organic Compounds	Polybutadiene derivative	Proprietary						0.012	mg	20000	64
supplier	Organic Compounds	Butadiene copolymer	Proprietary						0.009	mg	15000	48
supplier	Organic Compounds	Acrylate	Proprietary						0.023	mg	39000	125
supplier	Organic Compounds	Epoxy resin	Proprietary						0.012	mg	20000	64
supplier	Organic Compounds	Peroxide	Proprietary						0.005	mg	8000	26
supplier	Organic Compounds	Additive	Proprietary						0.011	mg	18000	58
supplier	Metals	Silver	7440-22-4						0.484	mg	820000	2632
Encapsulation (EME-G631BQ-CJ)	Other Organic Materials	85.690	mg	supplier	Organic Compounds	Epoxy resin	Proprietary		4.285	mg	50000	23306
				supplier	Organic Compounds	Phenol Resin	Proprietary		4.285	mg	50000	23306
				supplier	Organic Compounds	Silica, vitreous	60676-86-0		70.266	mg	820000	382222
				supplier	Glass	Silicon dioxide	7631-86-9		4.713	mg	55000	25637
				supplier	Glass	Aluminium hydroxide	21645-51-2		1.714	mg	20000	9322
				supplier	Organic Compounds	Carbon black	1333-86-4		0.300	mg	3500	1631
				supplier	Organic Compounds	Carbonato(2-)hexadecahydro	Proprietary		0.129	mg	1500	699
Bonding Wire (Cu)	Bonding Wire	0.668	mg	supplier	Metals	Copper	7440-50-8		0.645	mg	965500	3510
				supplier	Metals	Palladium	7440-05-3		0.021	mg	31000	113
				supplier	Metals	Gold	7440-57-5		0.002	mg	3500	13
Plating anode (Sn)	Other inorganic materials	1.528	mg	supplier	Metals	Tin	7440-31-5		1.528	mg	1000000	8310
Leadframe (C7025 + Ag)	Copper & its alloys	87.552	mg	supplier	Metals	Copper	7440-50-8		83.831	mg	957500	456011
				supplier	Metals	Magnesium	7439-95-4		0.131	mg	1500	714
				supplier	Metals	Nickel	7440-02-0		2.609	mg	29800	14192
				supplier	Metals	Silicon	7440-21-3		0.569	mg	6500	3096
				supplier	Metals	Silver	7440-22-4		0.411	mg	4700	2238